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Product Specification

AON7410

N-Channel Enhancement Mode MOSFET

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RoHS

Descriptions

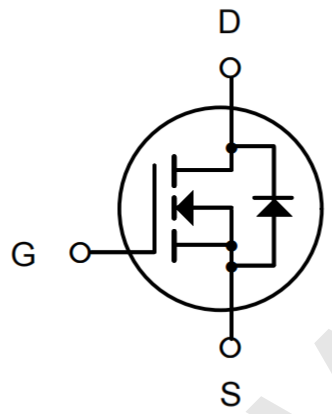
The AON7410 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

Features

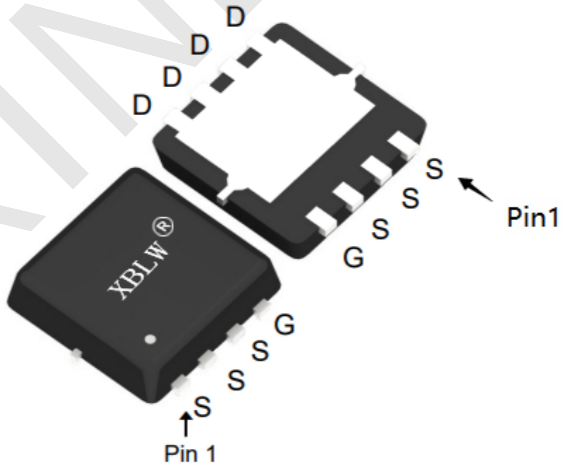
- V_{DS} = 30V,I_D = 30A
- $R_{DS(ON)}$ <13mΩ @ V_{GS}= 10V

Applications

- Battery protection
- Load switch
- Uninterruptible power supply



N-Channel MOSFET



DFN3X3-8L

Ordering Information

Product Model	Package Type	Marking	Packing	Packing Qty
AON7410	DFN3X3-8L	AON7410	Tape	5000Pcs/Reel

Absolute Maximum Ratings (T_C=25 °C unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@TC=25°C	Continuous Drain Current, V_{GS} @ 10V [1]	30	A
I_D@TC=100°C	Continuous Drain Current, V_{GS} @ 10V [1]	18	A
I_{DM}	Pulsed Drain Current	55	A
EAS	Single Pulse Avalanche Energy [3]	22.1	mJ
I_{AS}	Avalanche Current	21	A
P_D@TC=25°C	Total Power Dissipation [4]	20	W
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	75	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	6	°C/W

Electrical Characteristics (T_J=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=250uA	30	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BVDSS Temperature Coefficient	Reference to 25°C , I_D=1mA	---	0.022	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V , I_D=10A	---	8	13	mΩ
		V_{GS}=4.5V , I_D=5A	---	12	20	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =250uA	1.0	---	2.5	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.1	---	mV/°C
I_{DSS}	Drain-Source Leakage Current	V_{DS}=24V , V_{GS}=0V , T_J=25°C	---	---	1	uA
		V_{DS}=24V , V_{GS}=0V , T_J=55°C	---	---	5	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=5V , I_D=1A	---	4.5	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	2.5	---	Ω
Q_g	Total Gate Charge (4.5V)	V_{DS}=20V , V_{GS}=4.5V , I_D=10A	---	7.2	---	nC
Q_{gs}	Gate-Source Charge		---	1.4	---	
Q_{gd}	Gate-Drain Charge		---	2.2	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=12V , V_{GS}=10V , R_G=3.3Ω I_D=5A	---	4.1	---	ns
T_r	Rise Time		---	9.8	---	
$T_{d(off)}$	Turn-Off Delay Time		---	15.5	---	
T_f	Fall Time		---	6.0	---	
C_{iss}	Input Capacitance	V_{DS}=15V , V_{GS}=0V , f=1MHz	---	572	---	pF
C_{oss}	Output Capacitance		---	81	---	
C_{rss}	Reverse Transfer Capacitance		---	65	---	
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	28	A
I_{SM}	Pulsed Source Current[2,5]		---	---	55	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=1A , T_J=25°C	---	---	1.2	V

Note :

1.The data tested by surface mounted on a 1 $inch^2$ FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=21A.

4.The power dissipation is limited by 150°C junction temperature 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

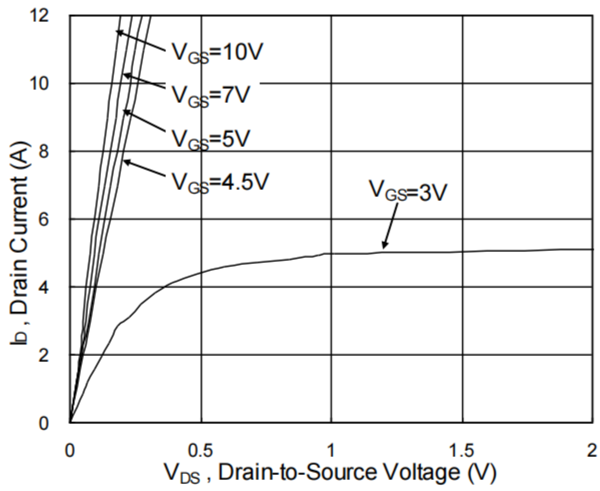


Fig 1. Typical Output Characteristics

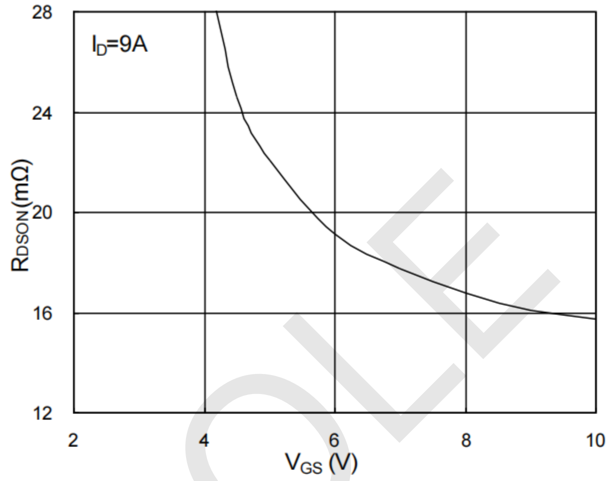


Fig 2. On-Resistance vs. Gate-Source

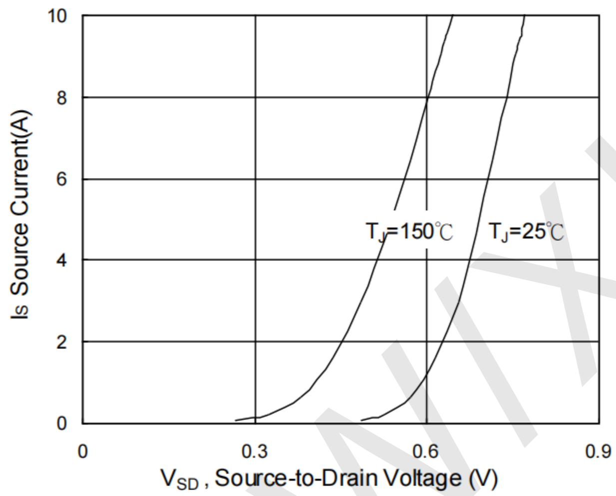


Fig 3. Forward Characteristics Of Reverse

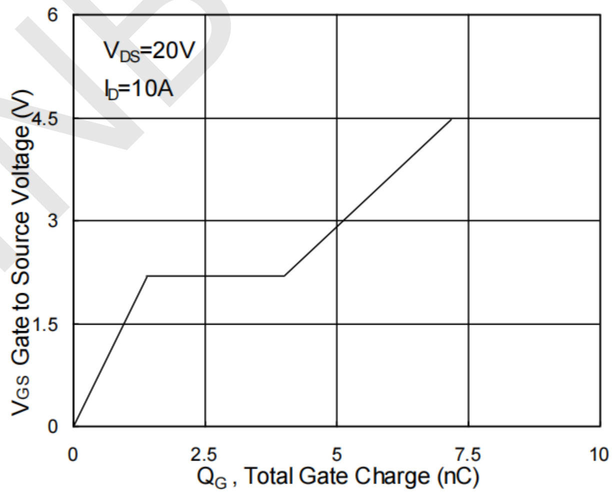


Fig 4. Gate-Charge Characteristics

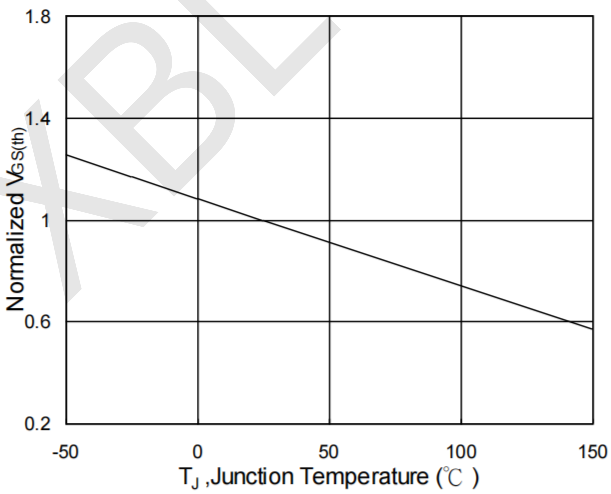


Fig 5. Normalized $V_{GS(th)}$ vs. T_J

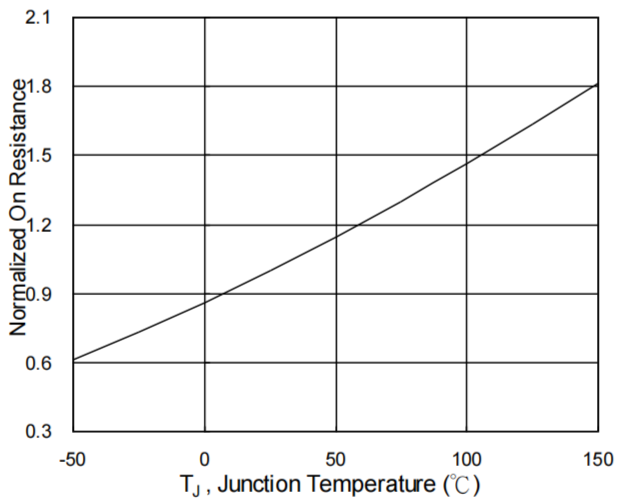


Fig 6. Normalized R_{DSON} vs T_J

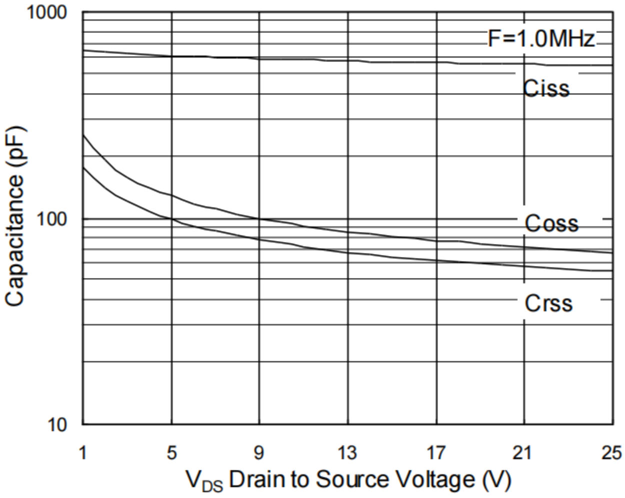


Fig 7. Capacitance

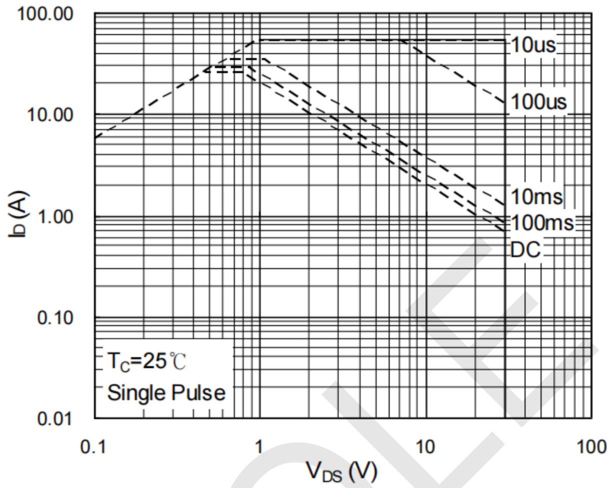


Fig 8. Safe Operating Area

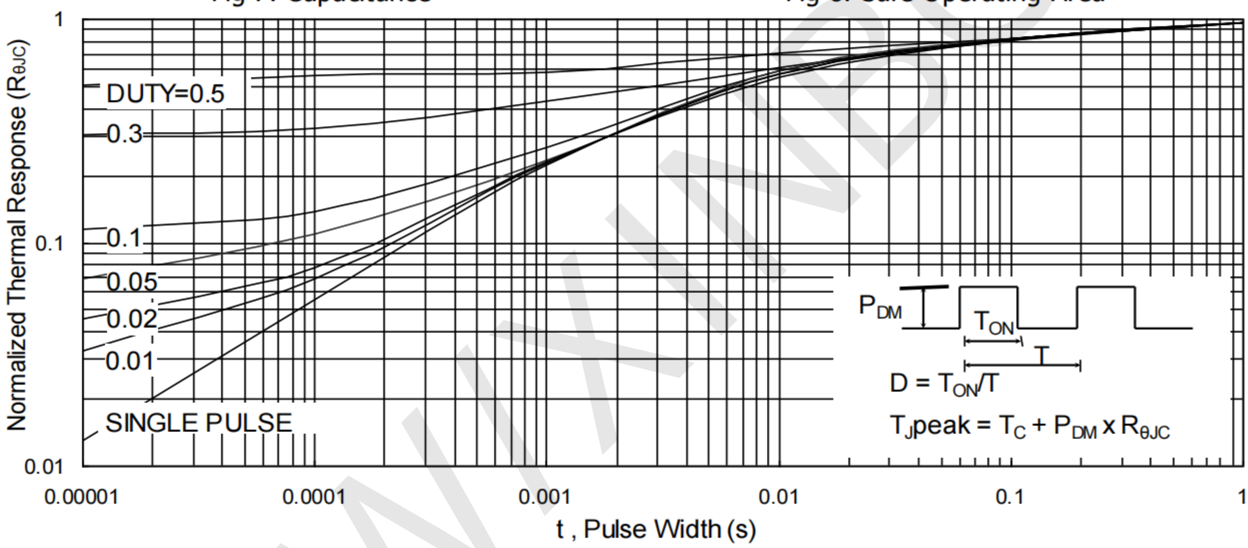


Fig 9. Normalized Maximum Transient Thermal Impedance

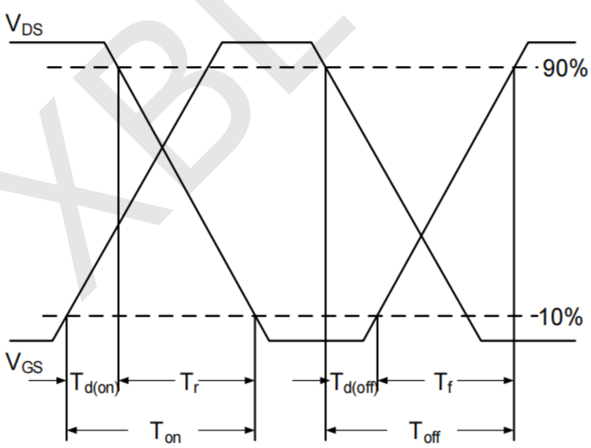


Fig 10. Switching Time Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

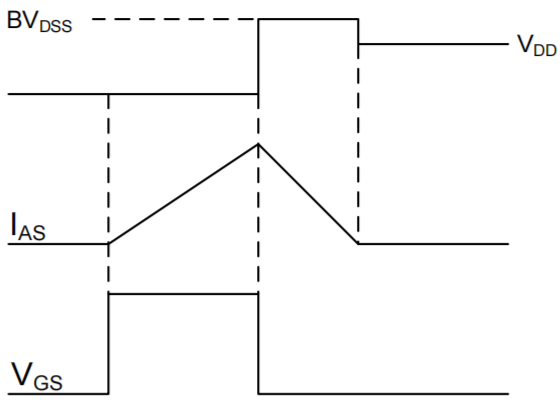
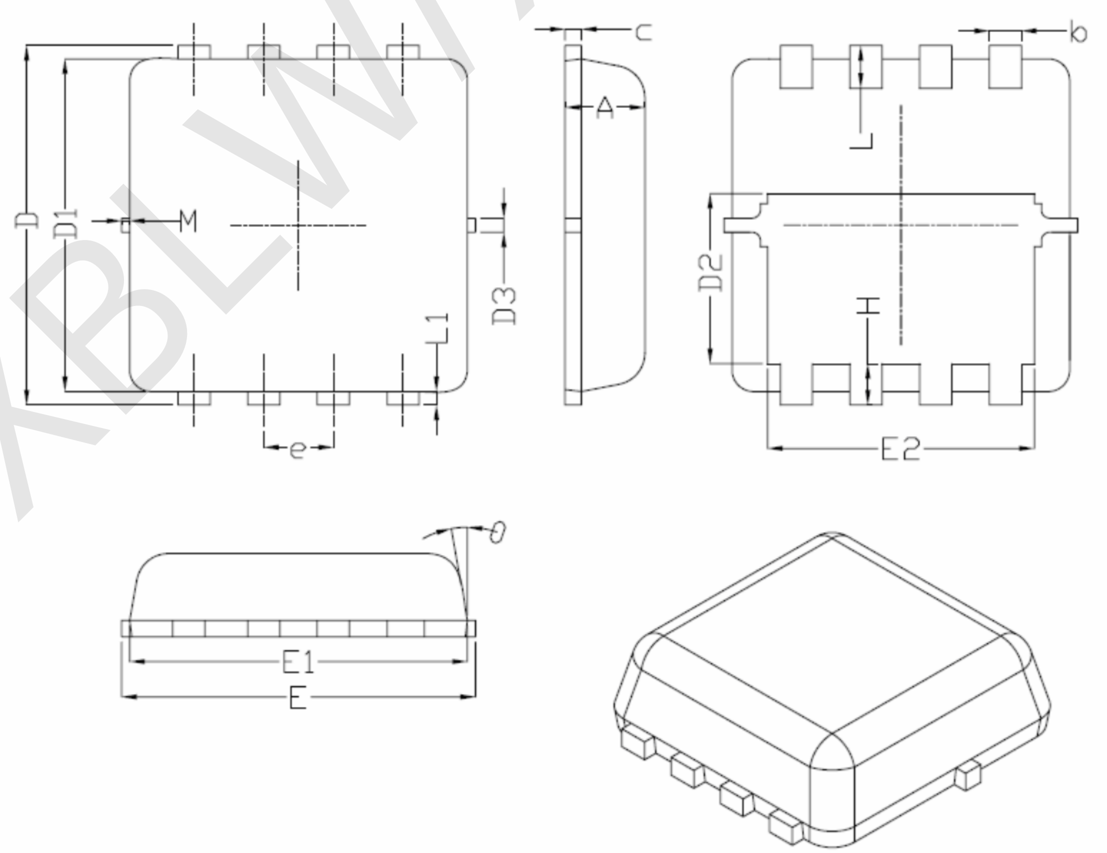


Fig 11. Unclamped Inductive Waveform

Package Information

DFN3X3-8L

Symbol	Dimensions In Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.48	1.58	1.68
D3	-	0.13	-
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	-	0.13	-
M	*	*	0.15
θ		10°	12°



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